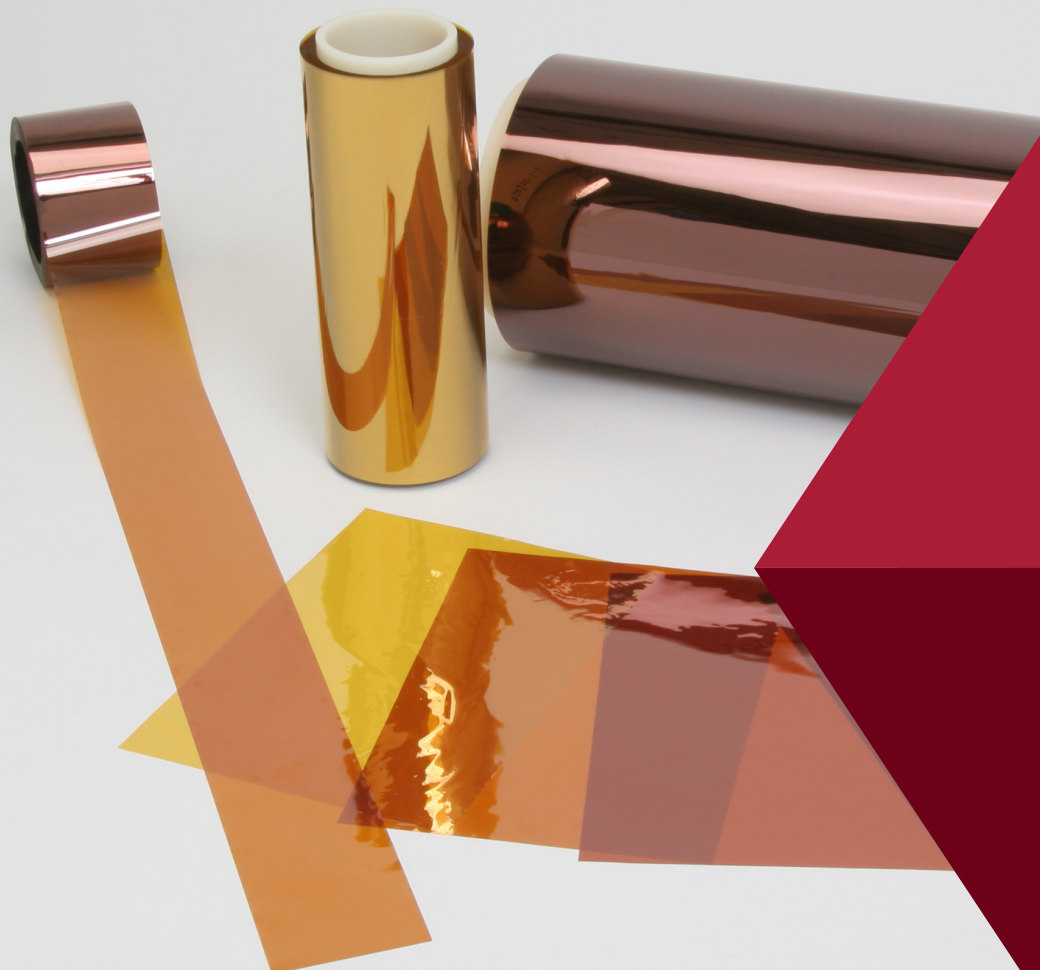




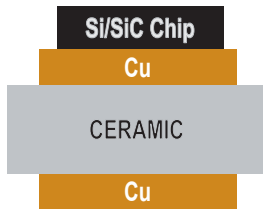
XENOMAX®

Polyimide Film



XENOMAX® heat dissipation substrate for Power Semiconductor Module

CERAMIC



Disadvantages

Heavy/Thick
Breakable
High Cost

VS.

XENOMAX®



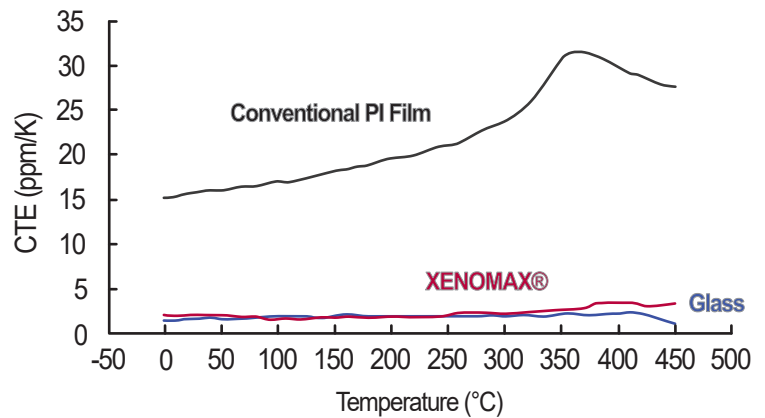
Advantages

Light/Thin
Unbreakable
Low Cost

Features

- » High heat stability
- » High flexibility
- » Flatness
- » Good processability
- » Thin
- » Very low CTE
- » Smooth surface

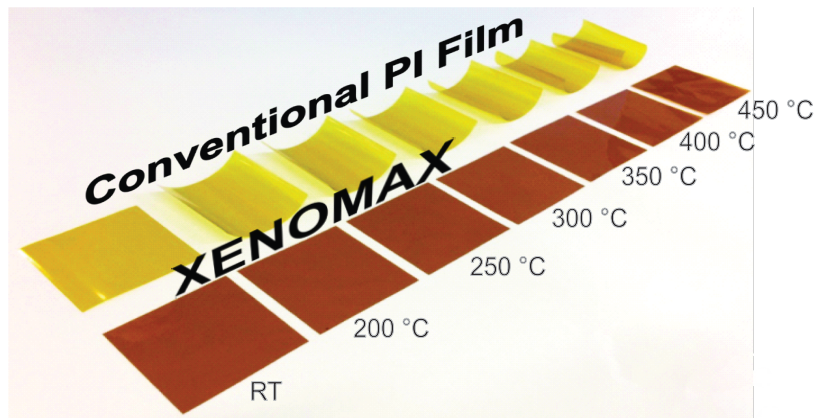
CTE same as glass over 500 °C which is available for LTPS



Available in sheet and/or roll



Outstanding high heat stability
compared to conventional PI film



	CERAMIC		XENOMAX®
	Al ₂ O ₃	Si ₃ N ₄	
CTE	7	3	3
Thickness (μm)	635	635	15
Thermal Conductivity (W/m*K)	24	90	0.2 (Z Direction)
Heat Resistance (m ² *K/W)	26 x 10 ⁻⁵	7 x 10 ⁻⁵	75 x 10 ⁻⁵
Dielectric Voltage (kV/mm)	15	13	250 (4 kV @ 15 μm)

* The values shown here are typical values, not guaranteed values.

